

UV-9300 Automatic UV Curing System (12"/300mm)

General Description

The UV-9300 is specially designed for the safe and reliable processing of 12" (300mm) wafers, with no contact between the operator and the wafer frame during processing. Based on AE's field-proven UV curing technology, the UV-9300 is easy to use and highly cost-effective to operate.

Windows™ Interface

The UV-9300 employs the simple-to-use, familiar Windows™ software interface. The Flat Panel Display shows UV intensity, irradiation time and other process parameters on-line, for comprehensive visual monitoring of system operation. Authorized operators can edit process parameters via the convenient Setup screen.

Safe, Ozone-free UV Light Source

The UV-9300 utilizes the optimized wavelength for the UV curing process. Low-pressure mercury vapor lamps do not require special cooling or exhaust systems to counteract harmful ozone emissions, providing a safe operating environment and economical utility requirements.

UV-9300 Features-at-a-Glance

- Fully Automatic, Continuous Processing Single-cassette Handling System.
- PC-controlled With Familiar Windows™ Software Interface.
- Full, On-line Process Monitoring With Dynamic Progress Diagram Display.
- Low Cost-of-Ownership - Requires No Nitrogen, Exhaust or Cooling Utilities.
- Safe, Ozone-free UV Irradiation Source.
- Processes 6", 8" and 12" Wafer Frames/Cassettes.
- Economical Footprint 58 x 111 cm.





AE International

USA, Canada and Mexico

AE North America
10 Dana Cres.,
Thornhill ON L4J 2R5 Canada
Fax / Phone: +1-905-709-7115
e-mail: sales@eshal.com

China

AE China
No. 419, New Caohejing Tower,
509 Cao Bao Road,
Shanghai, China P.C. 200233
Tel: +86-21-58319943
Fax: +86-21-58300346
Mobile: +86-139-18288377
e-mail: ae-china@eshal.com

Headquarters

AE Advanced Engineering
5 Hamada St., POB 787,
Migdal Haemek 23100
Israel
Tel: +972-4-6042604
Fax: +972-4-6042607
e-mail: info@eshal.com

For 12" (300 mm) Production Facilities, Operator and Environmentally Friendly

1. Wafer frames are automatically removed from wafer cassette for UV irradiation and returned to same cassette slot after processing.
2. Intelligent wafer frame handling system ensures continuous operation for maximum UV processing throughput.
3. Select tape type from pre-programmed choices for fast, simple UV irradiation process setup.
4. UV lamps are ozone-free for maximum operator safety and operating economy (no nitrogen or cooling facilities required).
5. UV lamp working time meter display indicates UV lamp replacement intervals to ensure consistent UV irradiation process performance.
6. The narrow UVA spectrum emitted by the UV lamps protects the wafer from irradiation overdose, since no infrared component is present (heat buildup can damage the UV tape adhesive).

Technical Specifications

Wafer/Frame size:	All standard sizes 6", 8" and 12"	
Effective UV wavelength:	365 nm	
Throughput:	8 minutes per 13-frame cassette •	
Control unit:	Pentium 4 PC, Windows™ 2000 Operating System	
Electrical utility:	110/240 Vac, 50/60 Hz	
Power:	1000 W (max.)	
UV Light Source:	Ozone-free, low pressure UV lamps	
Air:	72 p.s.i., c.d.a.	5 bar, c.d.a.
Dimensions:	56" (H) x 23" (W) x 44" (D)	141 (H) x 58 (W) x 111 cm (D)
Footprint:	23" x 44"	58 x 111 cm
Weight:	429 lbs.	195 kg

Specifications may be changed without prior notice.

- For silicon wafer, using UV tape requiring curing irradiation of 200 mJ/cm².

MICROTEST – ZA La Garrigue du Rameyron 84830 Sérignan – FRANCE

Tel : +33(0)4 90 40 60 90

Email : microtest@microtest-semi.com

Site web : www.microtest-semi.com